

In the Claims:

1. to 11. (Canceled)

12. (Currently Amended) A method for connecting an electrical energy storage device to an implantable medical device, comprising the step steps of:

- a) providing a bonding pad comprising:
 - i) a body having an intermediate surrounding side wall extending to and meeting with at least two spaced apart first and second contact walls; and
 - ii) a recess provided in at least one of the first and second contact walls of the bonding pad, the recess extending to and meeting with spaced apart portions of the surrounding side wall;
- b) moving a terminal lead of the electrical energy storage device into a nested position in the recess, the terminal lead comprising a terminal side wall extending along a longitudinal axis thereof, wherein a first portion of the terminal lead side wall extending along the longitudinal axis is received in the recess of the bonding pad to meet at least one of the spaced apart portions of the surrounding side wall and wherein a second portion of the terminal lead side wall extending along the longitudinal axis and opposite at least that part of the first portion meeting with the

one of the spaced apart portions of the surrounding side wall is exposed and not in contact with the bonding pad;

- c) securing the terminal lead to the bonding pad at least at a region where the one of the first and second contact walls having the recess meets the second portion of the terminal lead; and
- d) securing the other of the first and second contact wall walls not having the recess to the implantable medical device.

13. (Currently Amended) The method of claim ~~12~~ 16 including providing the recess as a channel extending to and meeting with at least two of the third and fourth side walls and the front and back walls.

14. (Original) The method of claim 12 including securing the terminal lead to the recess by one of welding, brazing, soldering, and an adhesive.

15. (Currently Amended) The method of claim 12 including securing the other of the first and second contact wall walls not having the recess to the implantable medical device by one of [a] welding, brazing, soldering, and an adhesive.

16. (New) The method of claim 12 including providing the bonding pad comprising spaced apart third and fourth side walls extending to and meeting with spaced apart front and back walls, and wherein the spaced apart first and second contact walls are joined to the third and fourth side walls and the front and back walls.

17. (New) The method of claim 12 including providing the spaced apart first and second contact walls being generally planar.

18. (New) The method of claim 17 including providing the planar first and second contact walls being parallel to each other.

19. (New) The method of claim 12 including providing the bonding pad of a material selected from the group consisting of nickel, a nickel alloy, a copper alloy, and a stainless steel alloy.

20. (New) The method of claim 12 including partially or completely plating the bonding pad.

21. (New) The method of claim 12 including at least partially plating the bonding pad with gold.

22. (New) The method of claim 12 including providing the terminal lead of a material selected from the group consisting of molybdenum, titanium, tantalum, 446 stainless steel, 29-4-2 stainless steel, 52 alloy, and mixtures thereof.

23. (New) A method for connecting an electrical energy storage device to an implantable medical device, comprising the steps of:

- a) providing a bonding pad comprising:
 - i) an intermediate surrounding side wall extending to and meeting with at least two spaced apart first and second contact walls; and
 - ii) a recess provided in at least one of the first and second contact walls of the bonding pad, the recess extending to and meeting with spaced apart portions of the surrounding side wall; and
- b) moving a terminal lead of the electrical energy storage device into a nested position in the recess, the terminal lead comprising a terminal side wall extending along a longitudinal axis thereof, wherein a first portion of the terminal lead side wall extending along the longitudinal axis is received in the recess of the bonding pad to meet at least one of the spaced apart portions of the surrounding side wall and wherein a second portion of the terminal lead side wall extending

along the longitudinal axis and opposite at least that part of the first portion meeting with the one of the spaced apart portions of the surrounding side wall is exposed and not in contact with the bonding pad;

- c) securing the terminal lead to the bonding pad at least at a region where the one of the first and second contact walls having the recess meets the second portion of the terminal lead;
- d) securing the other of the first and second contact walls not having the recess to the implantable medical device; and
- e) providing a second bonding pad comprising a second intermediate surrounding side wall extending to and meeting with at least two spaced apart third and fourth contact walls, wherein one of the third and fourth contact walls is directly connected to an enclosure for the electrical energy storage device and the other of the third and fourth contact walls is electrically connected to the implantable medical device.

24. (New) A method for connecting an electrical energy storage device to an implantable medical device, comprising the steps of:

- a) providing a bonding pad comprising:
 - i) an intermediate surrounding side wall extending to and meeting with at least two spaced apart first and second contact walls; and
 - ii) a recess provided in at least one of the first and second contact walls of the bonding pad, the recess extending to and meeting with spaced apart portions of the surrounding side wall; and
- b) moving a terminal lead of the electrical energy storage device into a nested position in the recess, the terminal lead comprising a terminal side wall extending along a longitudinal axis thereof, wherein a first portion of the terminal lead side wall extending along the longitudinal axis is received in the recess of the bonding pad to meet at least one of the spaced apart portions of the surrounding side wall and wherein a second portion of the terminal lead side wall extending along the longitudinal axis and opposite at least that part of the first portion meeting with the one of the spaced apart portions of the surrounding side wall is exposed and not in contact with the bonding pad;

- c) securing the terminal lead to the bonding pad at least at a region where the one of the first and second contact walls having the recess meets the second portion of the terminal lead; and
- d) directly contacting the other of the first and second contact walls not having the recess to an enclosure for the implantable medical device.